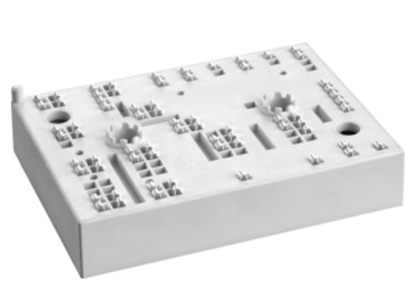


MiniSKiiP® 3

IGBT module

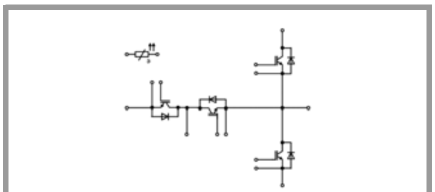
SKiiP 39TMLI12T4V2

Features*

- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Remarks*

- Case temperature limited to T_C= 125°C max.; T_C = T_S (valid for baseplateless modules)
- Product reliability results valid for T_j≤150°C (recommended T_{op}=-40...+150°C)
- IGBT 1: outer IGBTs T1&T4
- IGBT 2: inner IGBTs T2&T3
- Diode 1: outer diodes D1&D4
- Diode 2: inner diodes D2&D3
- $I_{t(RMS)}$ = 160A max. for power terminals



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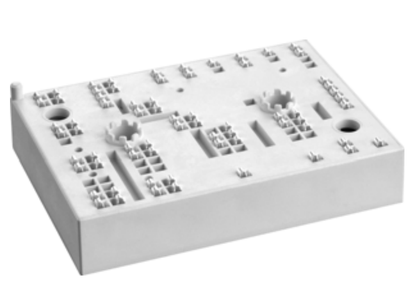
Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
IGBT1				
V_{CES}	T_j = 25 °C		1200	V
I_C	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	235	A
		T_s = 70 °C	191	A
I_C	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	290	A
		T_s = 70 °C	236	A
I_{Cnom}			200	A
I_{CRM}	I_{CRM} = 3 x I_{Cnom}		600	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 800 V, V_{GE} ≤ 15 V, T_j = 150 °C, V_{CES} ≤ 1200 V		6	µs
T_j			-40 ... 175	°C
IGBT2				
V_{CES}	T_j = 25 °C		650	V
I_C	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	207	A
		T_s = 70 °C	165	A
I_C	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	240	A
		T_s = 70 °C	192	A
I_{Cnom}			200	A
I_{CRM}	I_{CRM} = 3 x I_{Cnom}		600	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 360 V, V_{GE} ≤ 15 V, T_j = 150 °C, V_{CES} ≤ 650 V		6	µs
T_j			-40 ... 175	°C
Diode1				
V_{RRM}	T_j = 25 °C		1200	V
I_F	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	194	A
		T_s = 70 °C	154	A
I_F	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	224	A
		T_s = 70 °C	179	A
I_{Fnom}			200	A
I_{FRM}	I_{FRM} = 3 x I_{Fnom}		600	A
I_{FSM}	10 ms, sin 180°, T_j = 25 °C		990	A
T_j			-40 ... 175	°C
Diode2				
V_{RRM}	T_j = 25 °C		650	V
I_F	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	223	A
		T_s = 70 °C	174	A
I_F	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	255	A
		T_s = 70 °C	200	A
I_{Fnom}			200	A
I_{FRM}	I_{FRM} = 2 x I_{Fnom}		400	A
I_{FSM}	10 ms, sin 180°, T_j = 25 °C		1476	A
T_j			-40 ... 175	°C
Module				
$I_{t(RMS)}$			160	A
T_{stg}			-40 ... 125	°C
V_{isol}	AC sinus 50 Hz, t = 1 min		2500	V



MiniSKiiP® 3

IGBT module

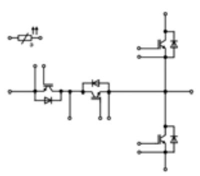
SKiiP 39TMLI12T4V2

Features*

- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Remarks*

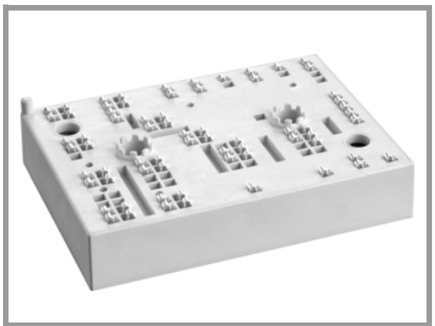
- Case temperature limited to T_C= 125°C max.; T_C = T_S (valid for baseplateless modules)
- Product reliability results valid for T_j≤150°C (recommended T_{op}=-40...+150°C)
- IGBT 1: outer IGBTs T1&T4
- IGBT 2: inner IGBTs T2&T3
- Diode 1: outer diodes D1&D4
- Diode 2: inner diodes D2&D3
- $I_{t(RMS)}$ = 160A max. for power terminals



TMLI

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
IGBT1						
$V_{CE(sat)}$	I_C = 200 A, V_{GE} = 15 V, chiplevel	T_j = 25 °C		1.80	2.05	V
		T_j = 150 °C		2.20	2.40	V
V_{CE0}	chiplevel	T_j = 25 °C		0.80	0.90	V
		T_j = 150 °C		0.70	0.80	V
r_{CE}	V_{GE} = 15 V, chiplevel	T_j = 25 °C		5.0	5.8	mΩ
		T_j = 150 °C		7.5	8.0	mΩ
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 12 mA		5	5.8	6.5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 1200 V, T_j = 25 °C				0.3	mA
C_{ies}	V_{CE} = 25 V, V_{GE} = 0 V	f = 1 MHz		12.30		nF
C_{oes}		f = 1 MHz		0.81		nF
C_{res}		f = 1 MHz		0.69		nF
Q_G	V_{GE} = - 8 V...+ 15 V			1130		nC
R_{Gint}	T_j = 25 °C			3.8		Ω
$t_{d(on)}$	V_{CE} = 300 V, I_C = 200 A, V_{GE} = +15/-15 V, $R_{G\,on}$ = 1.5 Ω, $R_{G\,off}$ = 1.5 Ω, di/dt_{on} = 2300 A/µs, di/dt_{off} = 1630 A/µs	T_j = 150 °C		186		ns
t_r		T_j = 150 °C		80		ns
E_{on}		T_j = 150 °C		7.5		mJ
$t_{d(off)}$		T_j = 150 °C		377		ns
t_f		T_j = 150 °C		109		ns
E_{off}		T_j = 150 °C		12.8		mJ
$R_{th(j-s)}$	per IGBT, λ_{paste}=0.8 W/(mK)			0.23		K/W
$R_{th(j-s)}$	per IGBT, λ_{paste}=2.5 W/(mK)			0.16		K/W
IGBT2						
$V_{CE(sat)}$	I_C = 200 A, V_{GE} = 15 V, chiplevel	T_j = 25 °C		1.45	1.85	V
		T_j = 150 °C		1.70	2.10	V
V_{CE0}	chiplevel	T_j = 25 °C		0.90	1.00	V
		T_j = 150 °C		0.82	0.90	V
r_{CE}	V_{GE} = 15 V, chiplevel	T_j = 25 °C		2.8	4.3	mΩ
		T_j = 150 °C		4.4	6.0	mΩ
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 3.2 mA		5	5.8	6.5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 650 V, T_j = 25 °C				0.3	mA
C_{ies}	V_{CE} = 25 V, V_{GE} = 0 V	f = 1 MHz		12.32		nF
C_{oes}		f = 1 MHz		0.77		nF
C_{res}		f = 1 MHz		0.37		nF
Q_G	V_{GE} = - 8 V...+ 15 V			1600		nC
R_{Gint}	T_j = 25 °C			1.0		Ω
$t_{d(on)}$	V_{CE} = 300 V, I_C = 200 A, V_{GE} = +15/-15 V, $R_{G\,on}$ = 2 Ω, $R_{G\,off}$ = 2 Ω, di/dt_{on} = 3300 A/µs, di/dt_{off} = 2200 A/µs	T_j = 150 °C		93		ns
t_r		T_j = 150 °C		62		ns
E_{on}		T_j = 150 °C		2		mJ
$t_{d(off)}$		T_j = 150 °C		295		ns
t_f		T_j = 150 °C		86		ns
E_{off}		T_j = 150 °C		9.3		mJ
$R_{th(j-s)}$	per IGBT, λ_{paste}=0.8 W/(mK)			0.33		K/W
$R_{th(j-s)}$	per IGBT, λ_{paste}=2.5 W/(mK)			0.26		K/W



MiniSKiiP® 3

IGBT module

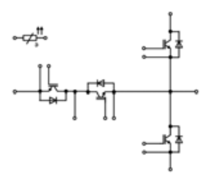
SKiiP 39TMLI12T4V2

Features*

- Robust and soft freewheeling diodes in CAL technology
- Highly reliable spring contacts for electrical connections
- UL recognised: File no. E63532

Remarks*

- Case temperature limited to T_C= 125°C max.; T_C = T_S (valid for baseplateless modules)
- Product reliability results valid for T_j≤150°C (recommended T_{op}=-40...+150°C)
- IGBT 1: outer IGBTs T1&T4
- IGBT 2: inner IGBTs T2&T3
- Diode 1: outer diodes D1&D4
- Diode 2: inner diodes D2&D3
- $I_{t(RMS)}$ = 160A max. for power terminals



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Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Diode1						
$V_F = V_{EC}$	I_F = 200 A V_{GE} = 0 V chiplevel	T_j = 25 °C		2.20	2.52	V
		T_j = 150 °C		2.15	2.47	V
V_{F0}	chiplevel	T_j = 25 °C		1.30	1.50	V
		T_j = 150 °C		0.90	1.10	V
r_F	chiplevel	T_j = 25 °C		4.5	5.1	mΩ
		T_j = 150 °C		6.3	6.9	mΩ
I_{RRM}	I_F = 200 A di/dt_{off} = 3700 A/µs V_R = 300 V V_{GE} = +15/-15 V	T_j = 150 °C		219		A
Q_{rr}		T_j = 150 °C		31		µC
E_{rr}		T_j = 150 °C		9.7		mJ
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			0.34		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			0.27		K/W
Diode2						
$V_F = V_{EC}$	I_F = 200 A V_{GE} = 0 V chiplevel	T_j = 25 °C		1.40	1.76	V
		T_j = 150 °C		1.38	1.77	V
V_{F0}	chiplevel	T_j = 25 °C		1.04	1.24	V
		T_j = 150 °C		0.85	0.99	V
r_F	chiplevel	T_j = 25 °C		1.78	2.6	mΩ
		T_j = 150 °C		2.7	3.9	mΩ
I_{RRM}	I_F = 200 A di/dt_{off} = 2200 A/µs V_R = 300 V V_{GE} = +15/-15 V	T_j = 150 °C		154		A
Q_{rr}		T_j = 150 °C		22.7		µC
E_{rr}		T_j = 150 °C		5.5		mJ
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			0.38		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			0.31		K/W
Module						
L_{sCE1}				-		nH
L_{CE}				-		nH
$R_{CC'+EE'}$		T_s = 25 °C		-		mΩ
		T_s = 125 °C		-		mΩ
M_s	to heat sink		2		2.5	Nm
M_t				-		Nm
						Nm
w				82		g
Temperature Sensor						
R_{100}	T_r=100°C (R_{25}=1000Ω)			1670 ± 3%		Ω
R(T)	$R_{(T)}$=1000Ω[1+A(T-25°C)+B(T-25°C)^2] , A = 7.635*10^{-3}°C^{-1}, B = 1.731*10^{-5}°C^{-2}					

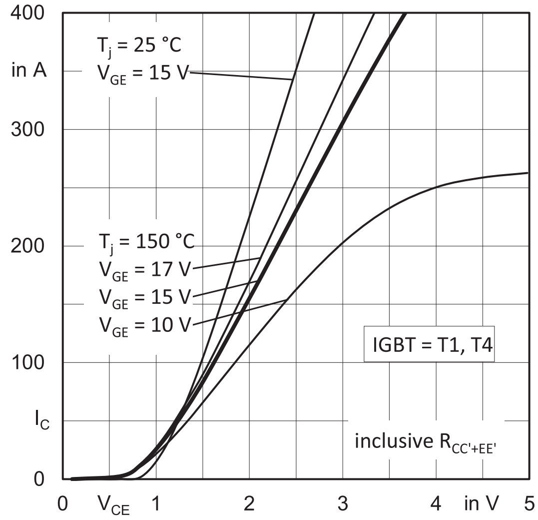


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+ EE'}$

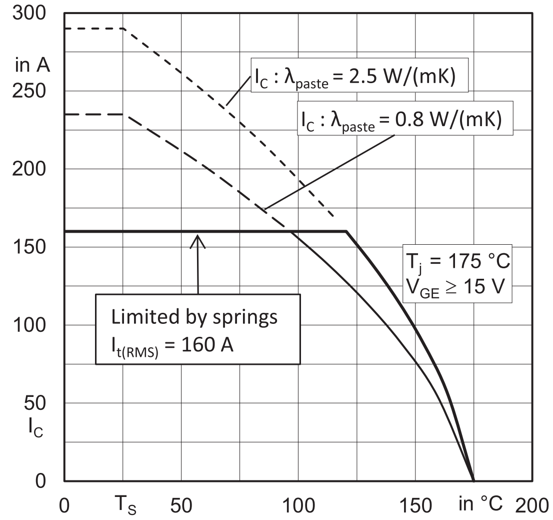


Fig. 2: IGBT1 rated current vs. Temperature I_c=f(T_s)

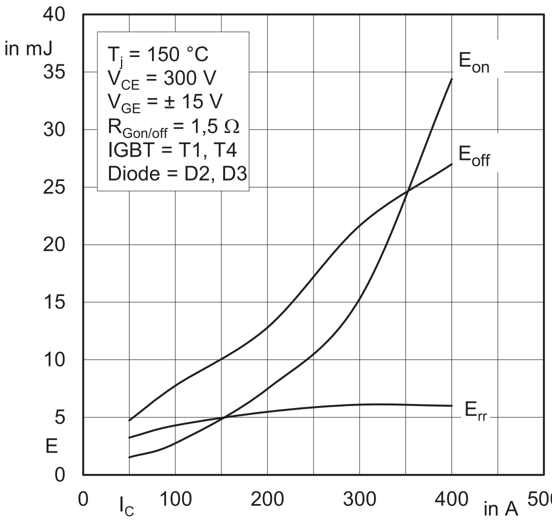


Fig. 3: Typ. IGBT1 & Diode2 turn-on /-off energy = f (I_C)

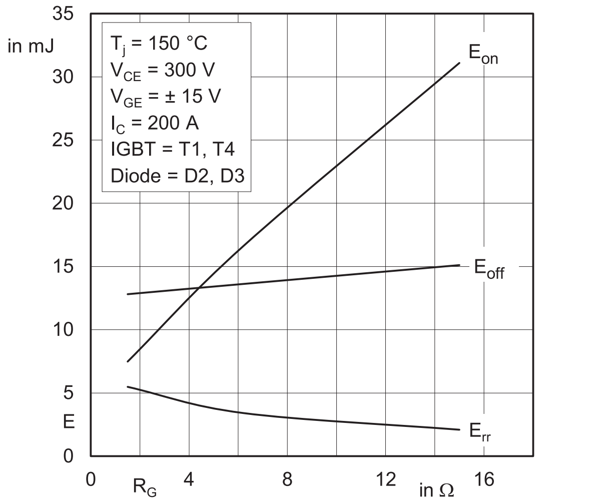


Fig. 4: Typ. IGBT1 & Diode2 turn-on /-off energy = f(R_G)

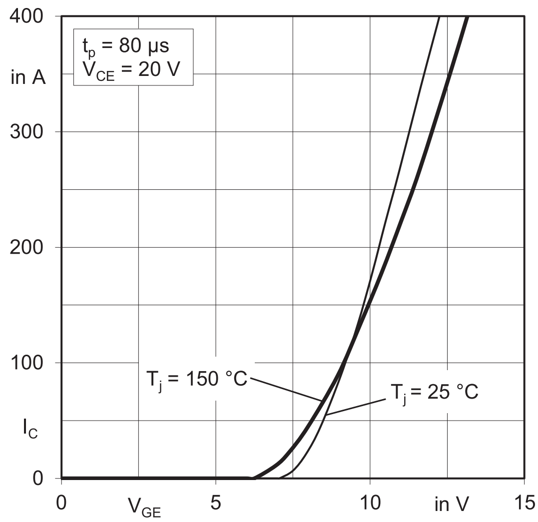


Fig. 5: Typ. IGBT1 transfer characteristic

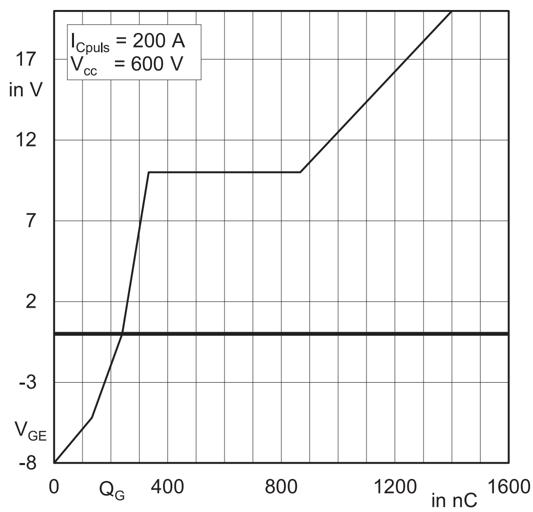


Fig. 6: Typ. IGBT1 gate charge characteristic

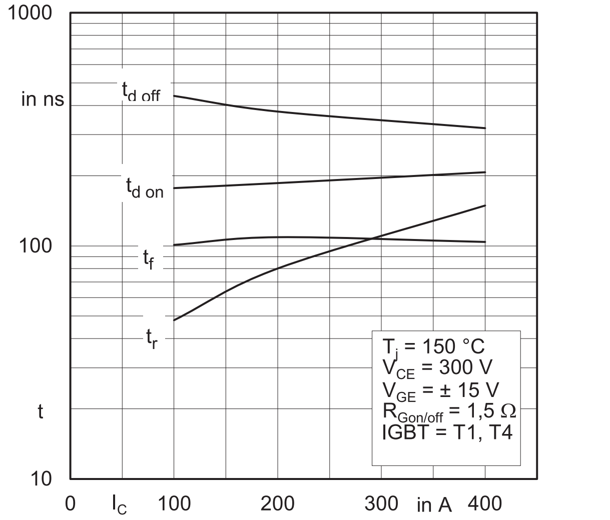


Fig. 7: Typ. IGBT1 switching times vs. I_C

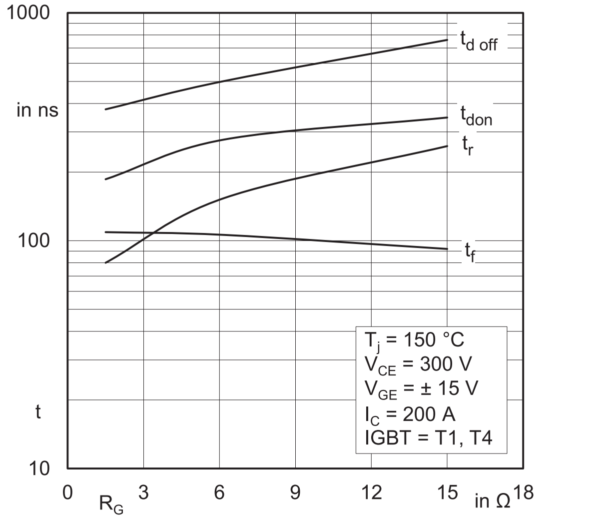


Fig. 8: Typ. IGBT1 switching times vs. gate resistor R_G

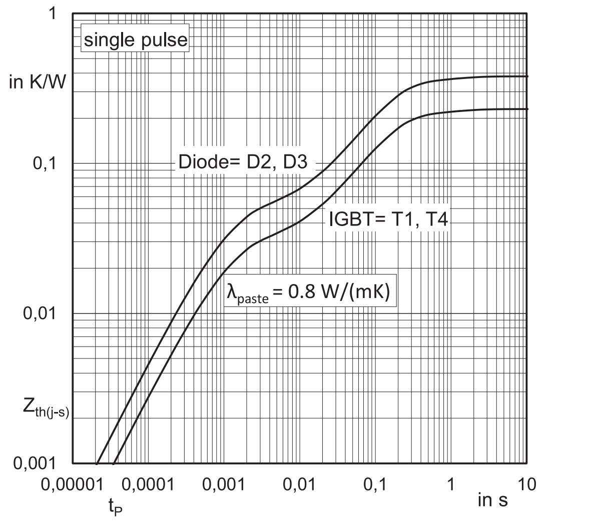


Fig. 9: Transient thermal impedance of IGBT1 & Diode2

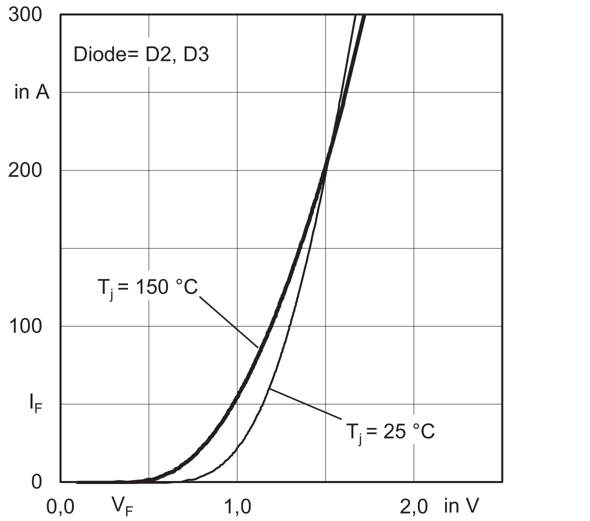


Fig. 10: Diode2 forward characteristic

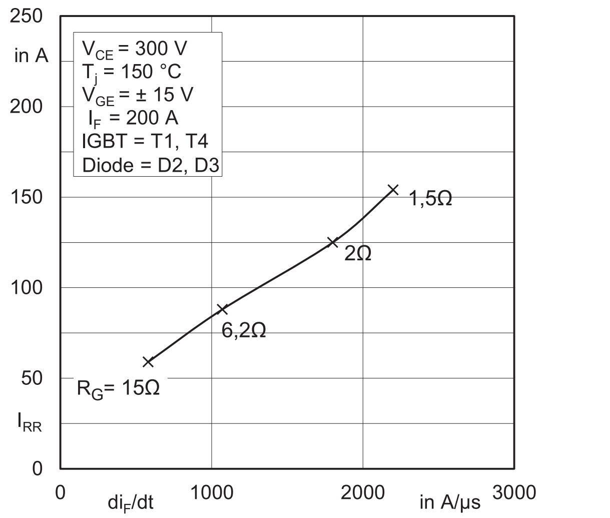


Fig. 11: Typ. Diode2 peak reverse recovery current

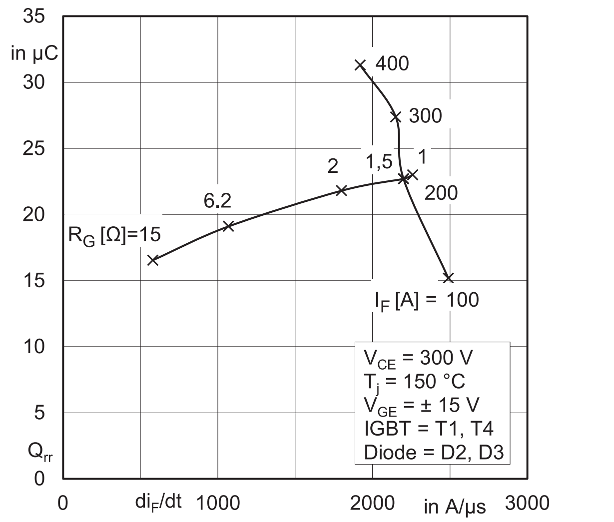


Fig. 12: Typ. Diode2 recovery charge

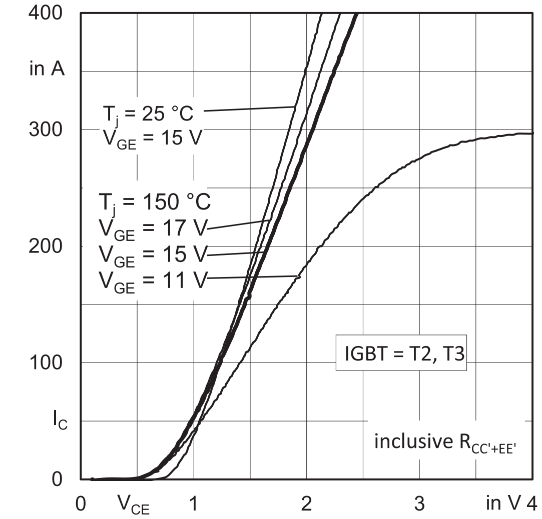


Fig. 13: Typ. IGBT2 output characteristic, incl. $R_{CC'+EE'}$

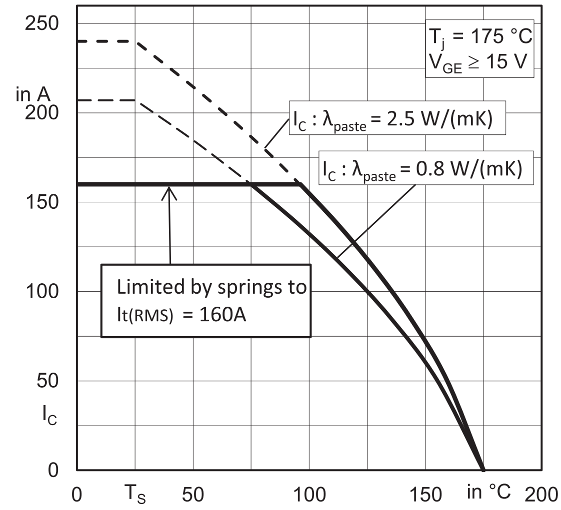


Fig. 14: Rated current vs. temperature I_C= f (T_s)

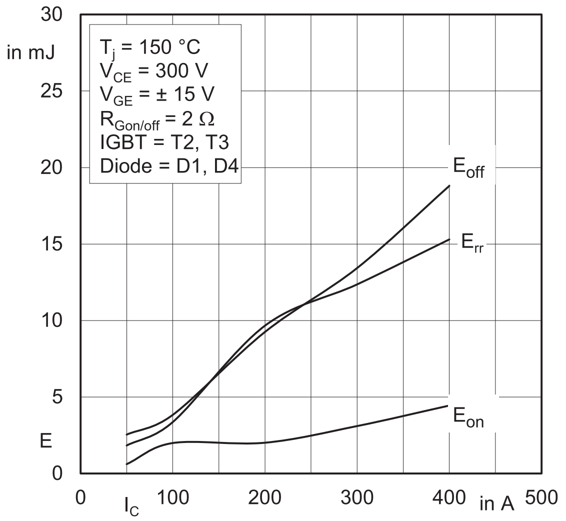


Fig. 15: Typ. IGBT2 & Diode1 turn-on /-off energy = f (I_C)

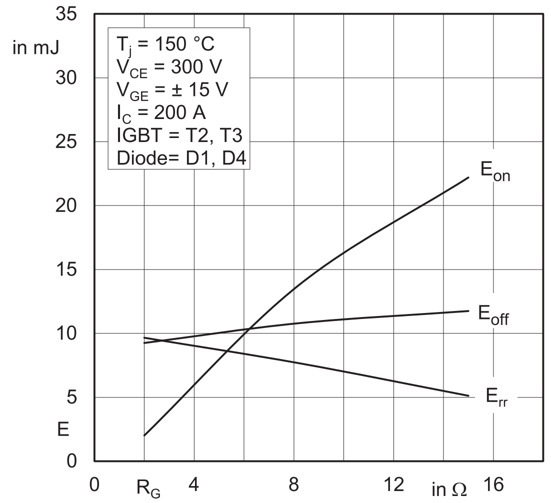


Fig. 16: Typ. IGBT2 & Diode1 turn-on / -off energy = f(R_G)

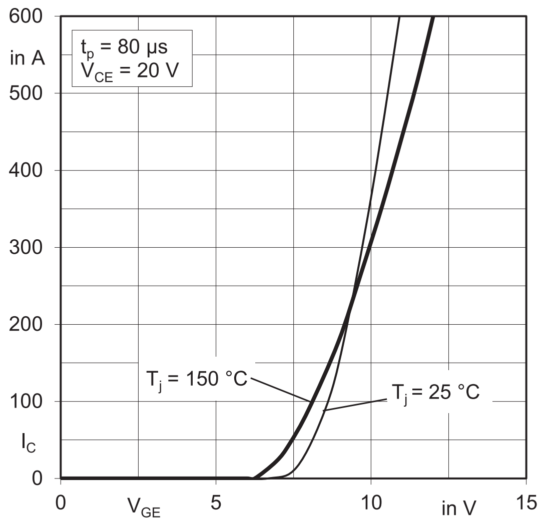


Fig. 17: Typ. IGBT2 transfer characteristic

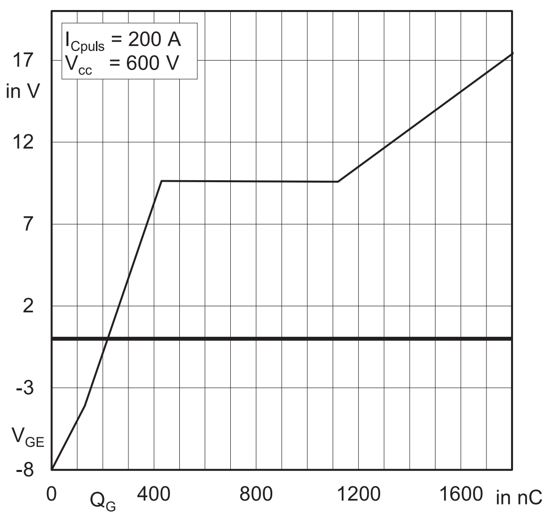


Fig. 18: Typ. IGBT2 gate charge characteristic

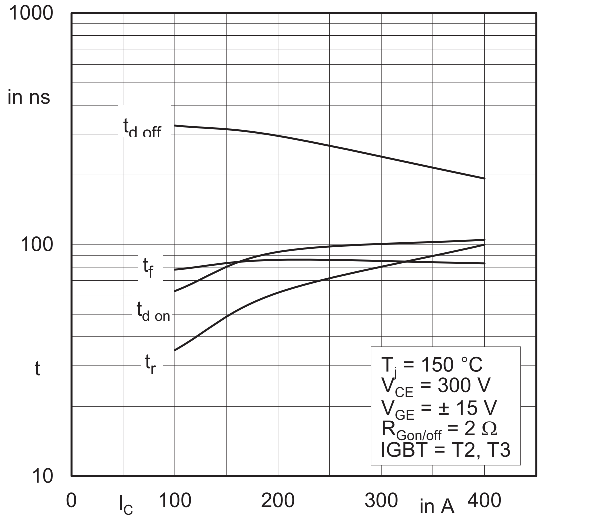


Fig. 19: Typ. IGBT2 switching times vs. I_C

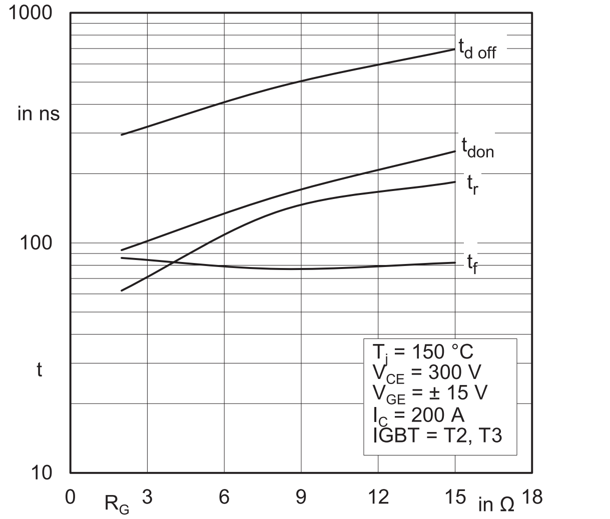


Fig. 20: Typ. IGBT2 switching times vs. gate resistor R_G

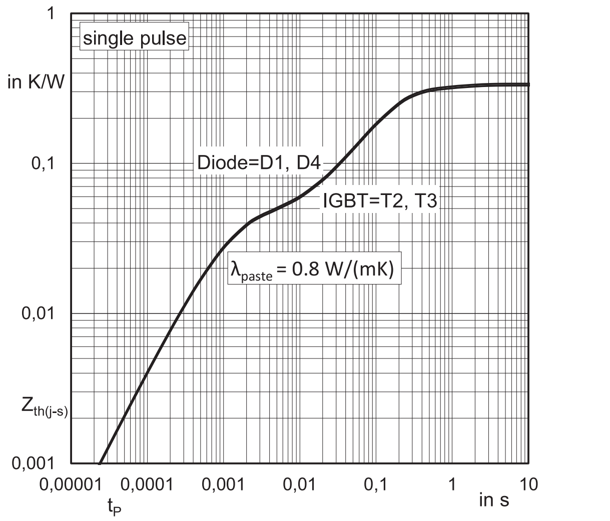


Fig. 21: Transient thermal impedance of IGBT2 & Diode1

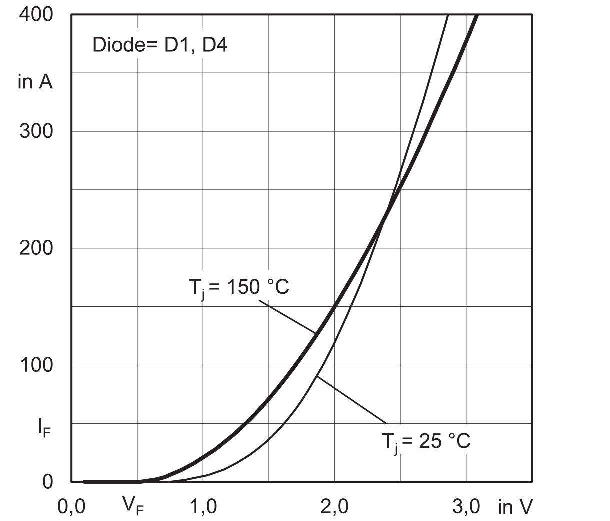


Fig. 22: Diode1 forward characteristic

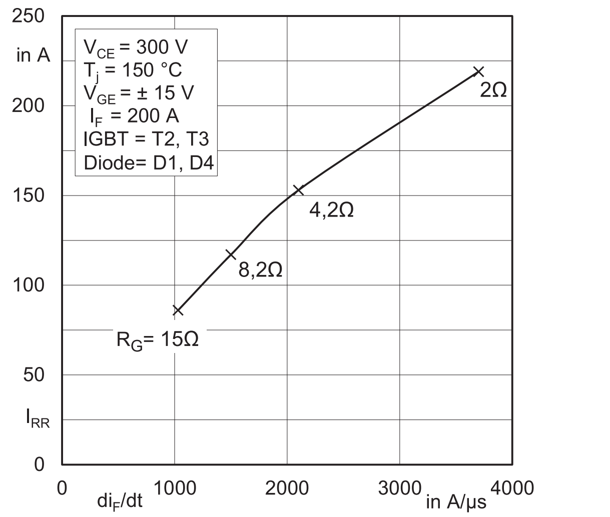


Fig. 23: Typ. Diode1 peak reverse recovery current

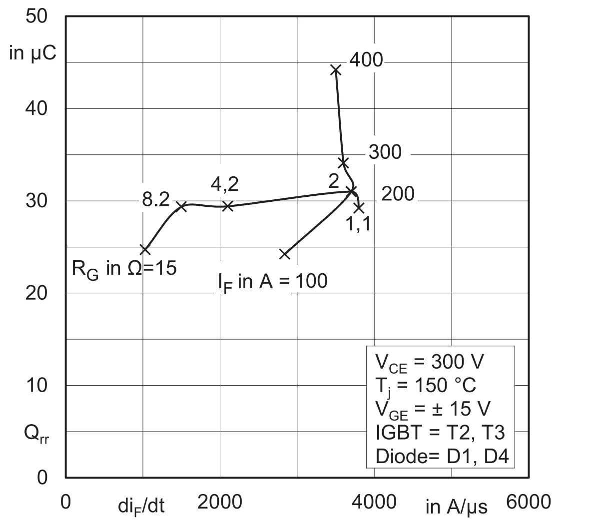
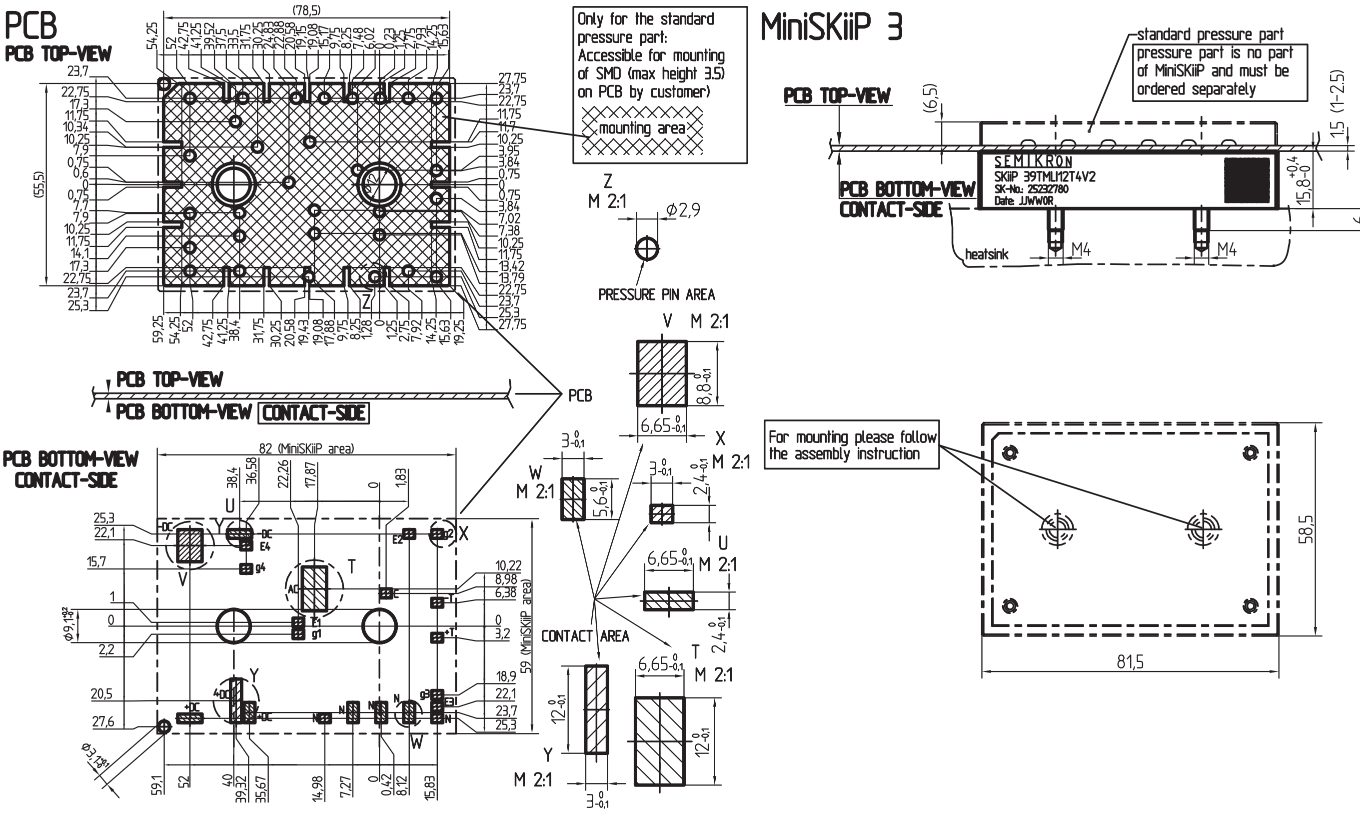
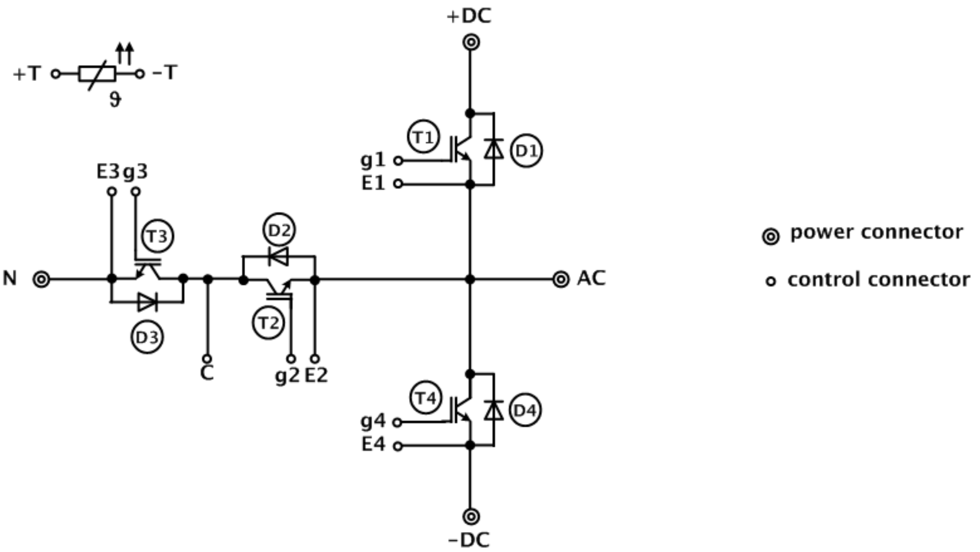


Fig. 24: Typ. Diode1 recovery charge



pinout, dimensions



pinout

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

***IMPORTANT INFORMATION AND WARNINGS**

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